

DFNW6 2.0x2.2, 0.65P CASE 507AF ISSUE O

DATE 18 AUG 2017

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.
- THIS DEVICE CONTAINS WETTABLE FLANK DESIGN FEATURE TO AID IN FILLET FORMA-TION ON THE LEADS DURING MOUNTING.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.80	0.85	0.90
A1			0.05
А3	0.20 REF		
A4	0.10		
b	0.20	0.25	0.30
D	1.90	2.00	2.10
D2	1.50	1.60	1.70
E	2.10	2.20	2.30
E2	0.79	0.89	0.99
е	0.65 BSC		
K	0.26 REF		
L	0.30	0.40	0.50
L3	0.05 REF		

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

= Date Code M = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

В ALTERNATE CONSTRUCTION **DETAIL A** PIN ONE REFERENCE EXPOSED COPPER **TOP VIEW** PLATING **DETAIL B** 0.05 C ALTERNATE CONSTRUCTION **DETAIL B** С 0.05 C SEATING PLANE NOTE 4 SIDE VIEW **PLATED** SURFACES DFTAIL A – D2 → SECTION C-C

RECOMMENDED SOLDERING FOOTPRINT*

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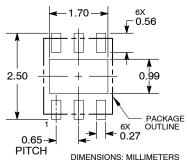
С 0.10

0.05 С NOTE 3

A B

е

BOTTOM VIEW



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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